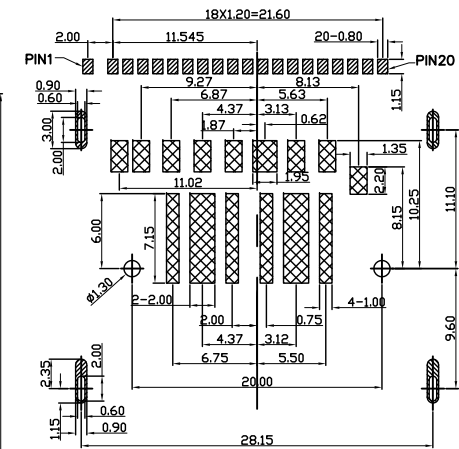
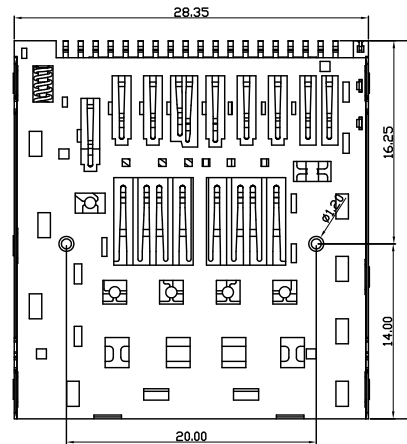
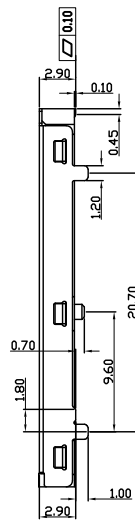
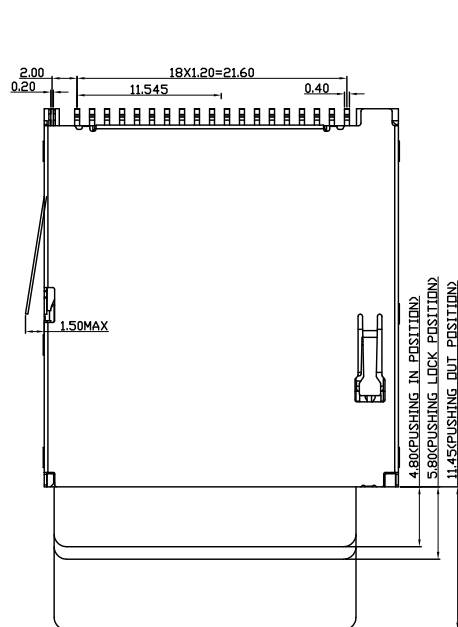
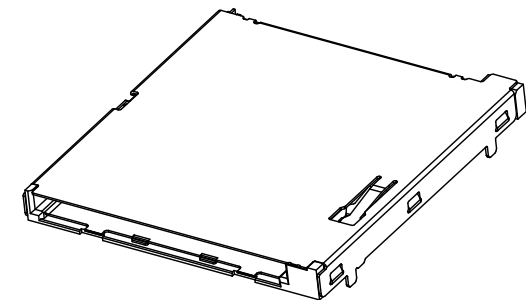




RECOMMENDED PCB LAYOUT
(ALL TOLERANCE ARE ± 0.05)

- PAD AREA
 NO TRACE, NO TEST POINT, NO VIA HOLE, NO GROUND AREA



NOTES :

- MATERIAL :
 - HOUSING: LCP S475 UL94 V-0, BLACK COLOR.
 - SHELL: STAINLESS STEEL SUS304.
 - CONTACT: COPPER ALLOY C5210.
- FINISH :
 - CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 100u" MIN ON SOLDER TAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - SHELL: 30u" MIN NICKEL PLATING OVERALL. Au 1u" MIN ON SOLDER TAIL AREA.
- ELECTRICAL CHARACTERISTICS:
 - OPERATING VOLTAGE : 100V AC(rms)/DC.
 - CURRENT RATING : 0.5 A.
 - OPERATING TEMPERATURE: $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$.
 - CONTACT RESISTANCE: 100 m OHMS MAX.
 - INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500 VAC/1MINUTE.

WITHOUT CARD		CARD INSERTED: LOCK	
C/D #12	VSS1 #11	C/D #12	VSS1 #11



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X $\pm$ 0.50	X* $\pm$ 5°	名 稱 (TITLE) SD4.0 Push H2.90 CONN	
.X $\pm$ 0.30	.X* $\pm$ 2°		
.XX $\pm$ 0.20	.XX* $\pm$ 1°		
單位 (UNIT) mm	料 號 (PART NO.) 7SD40-FA-0005	圖 號 (DWG NO.) 7SD40-FA-0005-A	比例 (SCALE) 1:1
審核 (APPROVAL)	校 對 (CHECKED)	製 圖 (DRAWN)	圖 數 (SHEET) 1/3
			更改 (REV) A

Pin Define

Connector PinNo.	Specifications SD4.0 PinNo.	Specifications MMC PinNo.	SD Mode			UHS-II Mode			MMC		
			Name	Type	Description	Name	Type	Description	Name	Type	Description
P1			WP			WP					
P2	P8		DAT1	I/O/PP	Data Line[Bit 1]	RCLK-	I				
P3	P7	P7	DAT0	I/O/PP	Data Line[Bit 0]	RCLK+	I		DAT	I/O/PP	Data
P4	P17		—		Not Used(Connected to ground)	VSS5	S	Supply voltage ground			
P5	P6	P6	VSS2	S	Supply voltage ground	VSS2	S	Supply voltage ground	VSS	S	Supply voltage ground
P6	P16		—		Not Used	D1+	LVDS				
P7	P5	P5	CLK	I	Clock	—		Not Used	CLK	I	Clock
P8	P15		—		Not Used	D1-	LVDS				
P9	P4	P4	VDD	S	Supply voltage	VDD1	S	Supply voltage(3.3V)	VDD	S	Supply voltage
P10	P14		—		Not Used	VDD2	S	Supply voltage(1.8V)			
P11	P3	P3	VSS1	S	Supply voltage ground	VSS1	S	Supply voltage ground	VSS	S	Supply voltage ground
P12			CD			CD					
P13	P13		—		Not Used(Connected to ground)	VSS4	S	Supply voltage ground			
P14	P2	P2	CMD	PP	Command/Response	—		Not Used	CMD	I/O/PP/OD	Command/Reserved
P15	P12		—		Not Used	D0-	LVDS				
P16	P1	P1	CD/DAT3	I/O/PP	Card Detect/ Data Line[Bit 3]	—		Not Used	RSV	NC	Reserved for future use
P17	P11		—		Not Used	D0+	LVDS				
P18	P9		DAT2	I/O/PP	Data Line[Bit 2]	—					
P19	P10		—		Not Used(Connected to ground)	VSS3	S	Supply voltage ground			
P20			GND			GND			GND		
P21			GND			GND			GND		
P22			GND			GND			GND		
P23			GND			GND			GND		
P24			GND			GND			GND		

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °		
.X± 0.30	.X*± 2 °		
.XX± 0.20	.XX*± 1 °		
		名 称(TITLE) SD4.0 Push H2.90 CONN	
单 位(UNIT) mm	料 号(PART NO.) 7SD40-FA-0005	图 号(DWG NO.) 7SD40-FA-0005-A	
审 核(APPROVAL)	检 核(CHECKED)	制 图(DRAWN)	比例 SCALE 1:1 图 数 SHEET 2/3 图 改 REV A

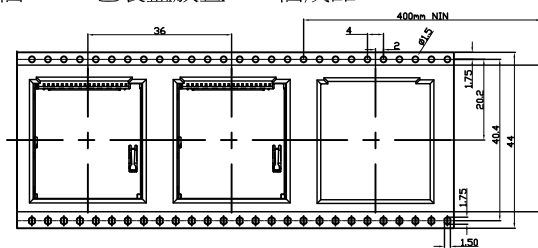


包裝作業規範

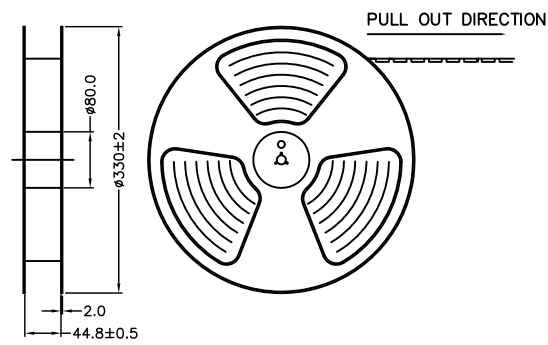
包裝作業圖示及說明

(PACKING OPERATION DIAGRAM & INSTRUCTION)

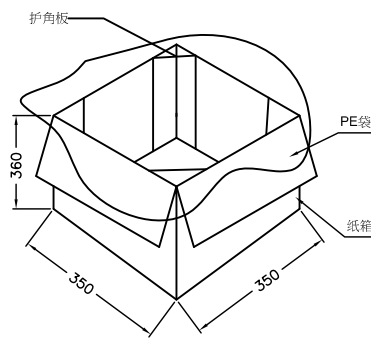
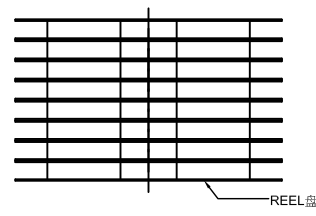
- 一.
- 1) 將成品一一放入REEL包裝盤內,依同一方向放入.
 - 2) 包裝時,如圖所示.
 - 3) 一個REEL包裝盤放置300 個成品.



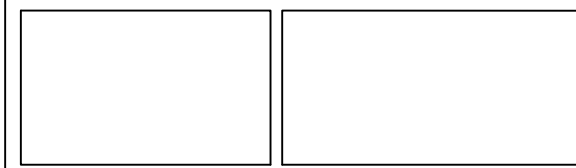
- 二.
- 1) 裝盤前先把前面空10pcs產品,然後再開始裝盤,尾端也需空10pcs產品,自粘帶加長200mm。
 - 2) 裝滿成品的REEL包裝盤如下圖所示。



- 三.
- 1) 每箱裝 7 盤REEL包裝盤.
 - 2) 每箱放置 2100 PCS 的成品.



- 四.
- 1) 用TAPE將紙箱封實.



備 註 (REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿.

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X± 0.50	X*± 5 °	名 稱(TITLE) SD4.0 Push H2.90 CONN	
.X± 0.30	.X*± 2 °		
.XX± 0.20	.XX*± 1 °		
單 位(UNIT) mm	料 號(PART NO.) 7SD40-FA-0005	圖 號(DWG NO.) 7SD40-FA-0005-A	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 1:1
			張 數 SHEET 3 / 3
			更 改 REV A

